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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/398,652	09/17/1999	WILLIAM A. SAMARAS	042390.P5120D	1359
7.	590 12/01/2003	EXAMINER		
JOHN F TRA	VIS	CHANG, RICK KILTAE		
BLAKELY SO	KOLOFF TAYLOR &	ZAFMAN		
12400 WILSHI	IRE BOULEVARD	ART UNIT	PAPER NUMBER	
SEVENTH FL	OOR	3729		
LOS ANGELE	S, CA 900251026			

DATE MAILED: 12/01/2003

Please find below and/or attached an Office communication concerning this application or proceeding.

		Applicat	ion No.	Applicant(s)				
Office Action Summary			652	SAMARAS ET AL.				
			er	Art Unit	<del></del>			
		Rick K. C	Chang	3729				
Period fo	The MAILING DATE of this communica or Reply	ition appears on th	e cover sheet with the	correspondence address				
THE - Exte after - If the - If NC - Failt - Any	ORTENED STATUTORY PERIOD FOR MAILING DATE OF THIS COMMUNICA nsions of time may be available under the provisions of 3 SIX (6) MONTHS from the mailing date of this community period for reply specified above is less than thirty (30) of the period for reply is specified above, the maximum statute reto reply within the set or extended period for reply will reply received by the Office later than three months after ed patent term adjustment. See 37 CFR 1.704(b).	ATION.  37 CFR 1.136(a). In no e cation.  lays, a reply within the state ory period will apply and wells apply and wells.	vent, however, may a reply be to atutory minimum of thirty (30) da will expire SIX (6) MONTHS fror plication to become ABANDON	imely filed  ys will be considered timely.  the mailing date of this communicati  ED (35 U.S.C. § 133).	ion.			
1)🛛	Responsive to communication(s) filed	on <u>16 September</u>	<u>2003</u> .					
2a)□	This action is <b>FINAL</b> . 2b)⊠ This action is non-final.							
3)□	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.							
Disposit	ion of Claims							
5)□ 6)⊠ 7)□	,							
Applicat	ion Papers							
10)	The specification is objected to by the E The drawing(s) filed on is/are: a Applicant may not request that any objection Replacement drawing sheet(s) including the The oath or declaration is objected to b	) accepted or b on to the drawing(s) e correction is requi	be held in abeyance. Seired if the drawing(s) is of	ee 37 CFR 1.85(a). bjected to. See 37 CFR 1.121				
	under 35 U.S.C. §§ 119 and 120							
a) 13)□ / s 3 a 14)□ /	Acknowledgment is made of a claim for All b) Some * c) None of:  1. Certified copies of the priority do 2. Certified copies of the priority do 3. Copies of the certified copies of application from the International See the attached detailed Office action for acknowledgment is made of a claim for a cince a specific reference was included in 7 CFR 1.78.  1) The translation of the foreign language acknowledgment is made of a claim for a ceremote was included in the first senter	cuments have be cuments have be the priority documents Bureau (PCT Rufor a list of the cert domestic priority un the first sentence lage provisional adomestic priority under the priority of the cuments of the priority of the cuments of the priority of the cuments of the cumen	en received. en received in Application to have been received in Application 17.2(a)). tified copies not receive ander 35 U.S.C. § 1190 to of the specification of the specification counter 35 U.S.C. §§ 1200 to the specification of the specification of the specification for the specification of the spec	tion No  ved in this National Stage  red. (e) (to a provisional applicator in an Application Data Stage  ceived. 0 and/or 121 since a specif	heet. fic			
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#### **DETAILED ACTION**

#### Continued Examination Under 37 CFR 1.114

1. A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on 9/16/03 has been entered.

### Claim Rejections - 35 USC § 103

- 2. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 3. Claims 19, 21 and 26 are rejected under 35 U.S.C. 103(a) as being unpatentable over Seidel (US 5,635,847) in view of Gedney et al (US 5,483,421), and further in view of Beers (US 5,680,936), Degani et al (US 5,990,564) and Hamzehdoost et al (US 5,689,091) and Mennitt et al (US 5,334,857).

Re claim 19: Seidel discloses providing an interposer (10); coupling solder balls (12) to the interposer (10) to selected locations; coupling a plurality of semiconductor dice (11) to the first surface (the surface where 11s are mounted); and testing the plurality of semiconductor dice (11) on the interposer (col. 1, lines 20-34 and col. 2, lines 46-51).

Seidel fails to disclose populating the second surface with a plurality of conductive pads; coupling the solder ball to only preselected conductive pads of the plurality of conductive pads

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that are intended to be used, the preselected conductive pads being less than all of the plurality of conductive pads; coupling a plurality of cache memory devices and at least one passive device to the first surface; coupling the interposer to a substrate with the solder balls after the testing if the plurality of semiconductor dice pass the testing; testing only a portion of those conductive pads that have solder balls attached to the plurality of conductive pads on the interposer; not coupling solder balls to non-selected locations; and coupling a microprocessor device to the substrate.

Gedney discloses populating the second surface with a plurality of conductive pads (32); coupling a solder ball (44) to each of preselected ones of the plurality of conductive pads (32); coupling the interposer (24) to a substrate (38) with the solder balls (44); and coupling at least one other semiconductor device (Fig. 4 shows a third semiconductor device (20 and 24) is mounted on 38) to the substrate (38) thereby forming a multi-chip subassembly and mounting this subassembly to printed circuit cards (col. 1, lines 7-8) without any defective components.

Beers discloses coupling at least one passive device (see annotated Fig. 3 below) thereby regulating voltage and current to the electronic dice.

Hamzehdoost discloses not coupling solder balls to non-selected locations (the conductive metal layer 30 is covered with a compatible material, except for selective solerable areas 36 where it is desired to have the solder balls applied (col. 3, lines 47-450) and see col. 3, lines 61-63) thereby saving production cost and making the package lighter for saving fuel cost.

Degani discloses mounting a plurality of cache memory devices and a microprocessor device on an interposer to use in a computer to perform computation and temporarily store program applications.

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Mennitt discloses coupling the solder ball to only preselected conductive pads of the plurality of conductive pads that are intended to be used, the preselected conductive pads being less than all of the plurality of conductive pads (Figs. 2 and 5 show connecting the solder ball to only preselected conductive pads of the plurality of conductive pads that are intended to be used, the preselected conductive pads being less than all of the plurality of conductive pads).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Seidel by populating the second surface with a plurality of conductive pads; coupling a solder ball to each of preselected ones of the plurality of conductive pads; coupling the interposer to a substrate with the solder balls; and coupling at least one other semiconductor device to the substrate, as taught by Gedney, for the purpose of forming a multi-chip subassembly and mounting this subassembly to printed circuit cards without any defective components.

Further, it would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Seidel by not coupling solder balls to non-selected locations, as taught by Hamzehdoost, for the purpose of saving production cost and making the package lighter for saving fuel cost.

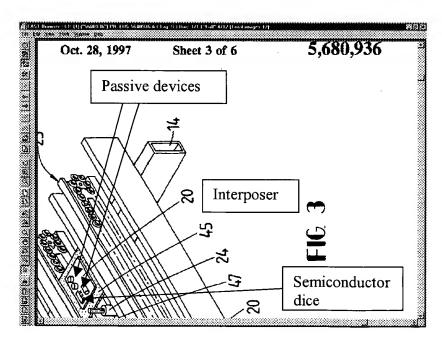
Furthermore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Seidel by coupling at least one passive device to the first surface of the interposer, as taught by Beers, for the purpose of regulating voltage and current to the electronic chip.

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Seidel by coupling the solder ball to only preselected conductive pads of the

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plurality of conductive pads that are intended to be used, the preselected conductive pads being less than all of the plurality of conductive pads, as taught by Mennitt, for the purpose of saving space and production cost by eliminating solder balls which are not needed by the device user.

In addition, it would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Seidel by mounting a plurality of cache memory devices and a microprocessor device, as taught by Degani, to use in a computer to perform computation and temporarily store program applications.



Re claim 21: Seidel teaches the invention as described with respect to claim 19 above. Seidel fails to disclose providing the interposer having organic material.

Gedney discloses providing the interposer (24) having organic material (col. 7, lines 15-16) thereby providing low thermal coefficient of expansion.

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It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Seidel by providing the interposer having organic material, as taught by Gedney, for the purpose of providing low thermal coefficient of expansion.

Re claim 26: Seidel teaches the invention as described with respect to claim 19 above.

Seidel fails to disclose creating a plurality of contacts on the substrate; and electrically connecting the preselected conductive pads to the plurality of contacts.

Mennitt discloses creating a plurality of contacts (16) on the substrate (12) and electrically connecting the selected ones of the plurality of conductive pads to the plurality of contacts (Fig. 3).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Seidel by creating a plurality of contacts on the substrate; and electrically connecting the preselected conductive pads to the plurality of contacts, as taught by Mennitt, for the purpose of allowing signal to travel from one part of the component to another and providing power and ground to the device.

NOTE: Please provide reference numerals (either in parentheses next to the claimed limitation or in a table format with one column listing the claimed limitation and another column listing corresponding reference numerals in the remark section of the response to the Office Action) to all the claimed limitations as well as support in the disclosure for better clarity. Applicants are duly reminded that a full and proper response to this Office Action that includes any amendment to the claims and specification of the application as originally filed requires that the applicant point out the support for any amendment made to the disclosure, including the claims. See 37 CFR 1.111 and MPEP 2163.06.

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## Response to Arguments

4. Applicant's arguments with respect to claims 19, 21 and 26 have been considered but are most in view of the new ground(s) of rejection.

#### Conclusion

- 5. Please provide reference numerals (either in parentheses next to the claimed limitation or in a table format with one column listing the claimed limitation and another column listing corresponding reference numerals in the remark section of the response to the Office Action) to all the claimed limitations as well as support in the disclosure for better clarity. Applicants are duly reminded that a full and proper response to this Office Action that includes any amendment to the claims and specification of the application as originally filed requires that the applicant point out the support for any amendment made to the disclosure, including the claims. See 37 CFR 1.111 and MPEP 2163.06.
- 6. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Rick K. Chang whose telephone number is (703) 308-4784. The examiner can normally be reached on 5:30 AM to 1:30 PM, Monday through Thursday.

The fax phone numbers for the organization where this application or proceeding is assigned are (703) 872-9302 for regular communications and (703) 872-9303 for After Final communications.

RICHARD CHANG PRIMARY EXAMINER Page 7